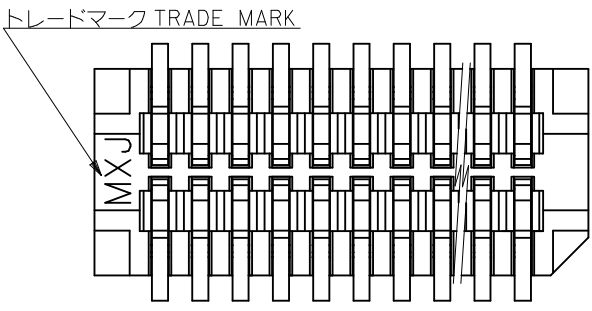


注記 NOTES
 1. 嵌合相手: 52465, 52588 シリーズ
 MATES WITH : 52465, 52588 SERIES
 2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
 SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
 3. ELV 及び RoHS 適合品。
 ELV AND ROHS COMPLIANT.
 4. テール平坦度: 0.1MAX.
 COPLANARITY : 0.1MAXIMUM

0.4	17.8	16.9	15.2	—————	53353-4071	40
0.4	16.2	15.3	13.6	—————	53353-3671	36
0.8	13.8	12.9	11.2	53353-3029	53353-3071	30
0.4	13.0	12.1	10.4	—————	53353-2871	28
0.8	10.6	9.7	8.0	—————	53353-2271	22
0.4	9.8	8.9	7.2	—————	53353-2071	20
0.8	9.0	8.1	6.4	—————	53353-1871	18
0.4	8.2	7.3	5.6	—————	53353-1671	16
0.8	7.4	6.5	4.8	—————	53353-1471	14
0.4	6.6	5.7	4.0	—————	53353-1271	12
0.8	5.8	4.9	3.2	—————	53353-1071	10
D	C	B	(A)	TRAY PACKAGE	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.		CIRCUIT
				CONNECTOR SERIES No. : 53353-**29		

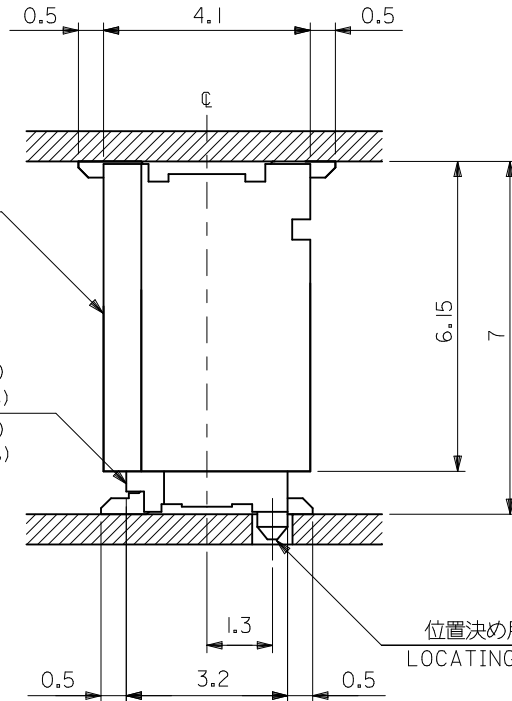


REVISED EC NO: J2011-0630 DRWN:KTOYODA 2010/11/01 CHKD:MSASAO 2010/11/01 APPR:MSASAO 2010/11/01	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE METRIC		DESIGN UNITS THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/3/4	TITLE 0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)			
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/3/4	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/3/4	DOCUMENT NO. SD-53353-003			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

53353-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

嵌合相手 MATES WITH
52465-***19 (位置決め用ボス付)
(WITH LOCATING BOSS)

52465-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

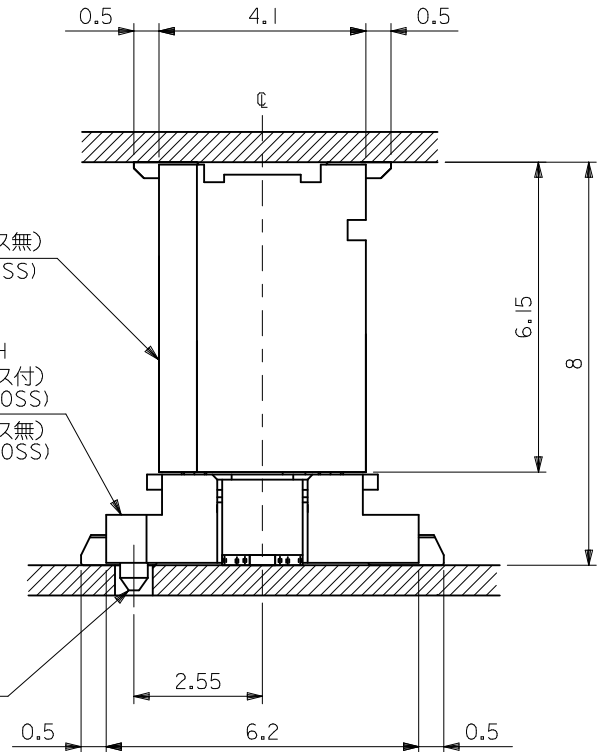


53353-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

嵌合相手 MATES WITH
52588-**** (位置決め用ボス付)
(WITH LOCATING BOSS)

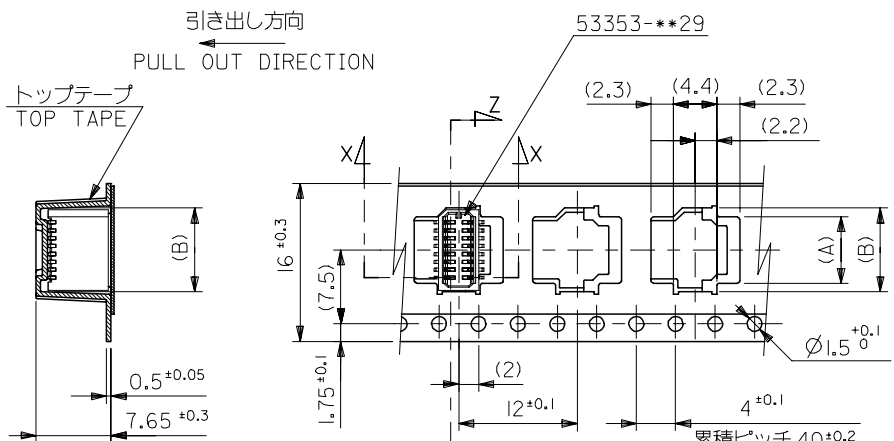
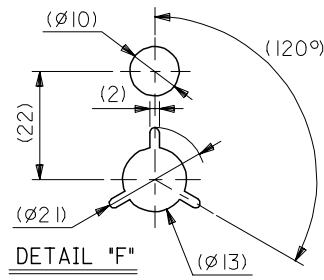
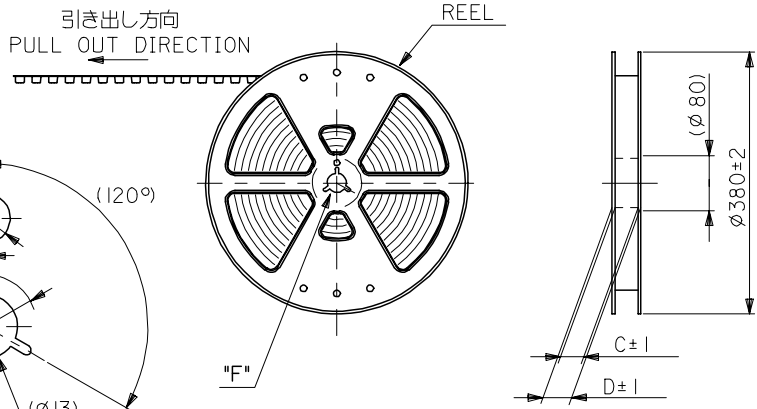
52588-**** (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

位置決め用ボス
LOCATING BOSS

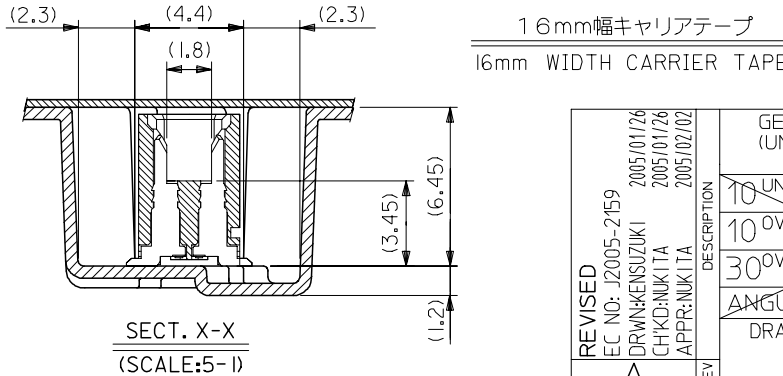


嵌合状態図 (参考)
MATED DRAWING (REF.)

REVISED EC NO: J2011-0630 DRW:KTOYODA 2010/11/01 CHK:DMSASAO 2010/11/01 APPR:MSASAO 2010/11/01	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. : 53353-***29			
		10 UNDER	± ---	DRAWN BY Y. WADA	DATE 2004/3/4	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 OVER 30 UNDER	± ---	CHECKED BY M. SASAO	DATE 2004/3/4	TITLE 0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)			
		30 OVER	± ---	APPROVED BY M. SASAO	DATE 2004/3/4	MOLEX INCORPORATED			
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53353-003		SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



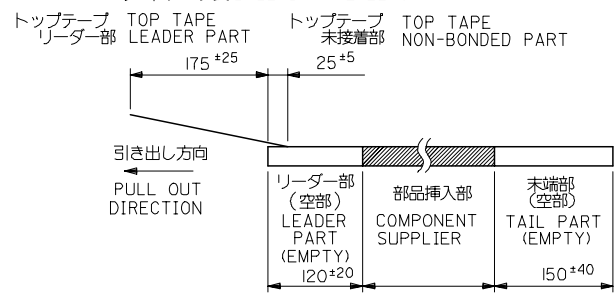
SECT. Z-Z



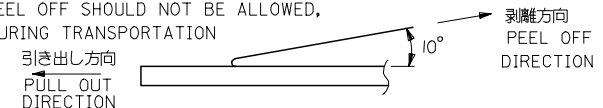
SECT. X-X
(SCALE:5-1)

注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：(剥離方向は下図参照)
0. 1~1. 3N {10~130gf} 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
PEELING OFF FORCE OF TOP TAPE
0. 1~1. 3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION

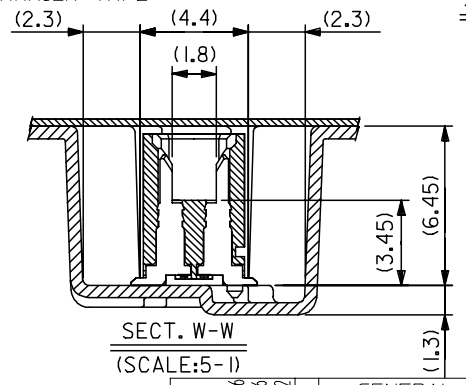
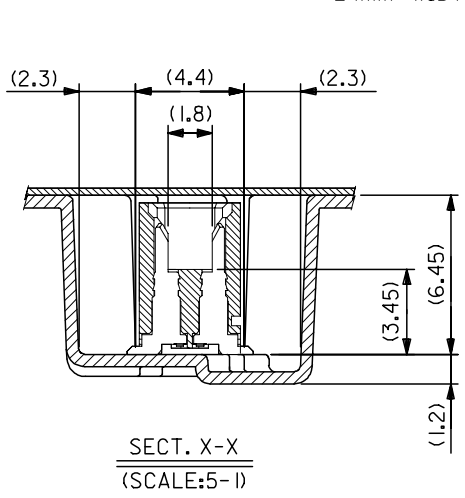
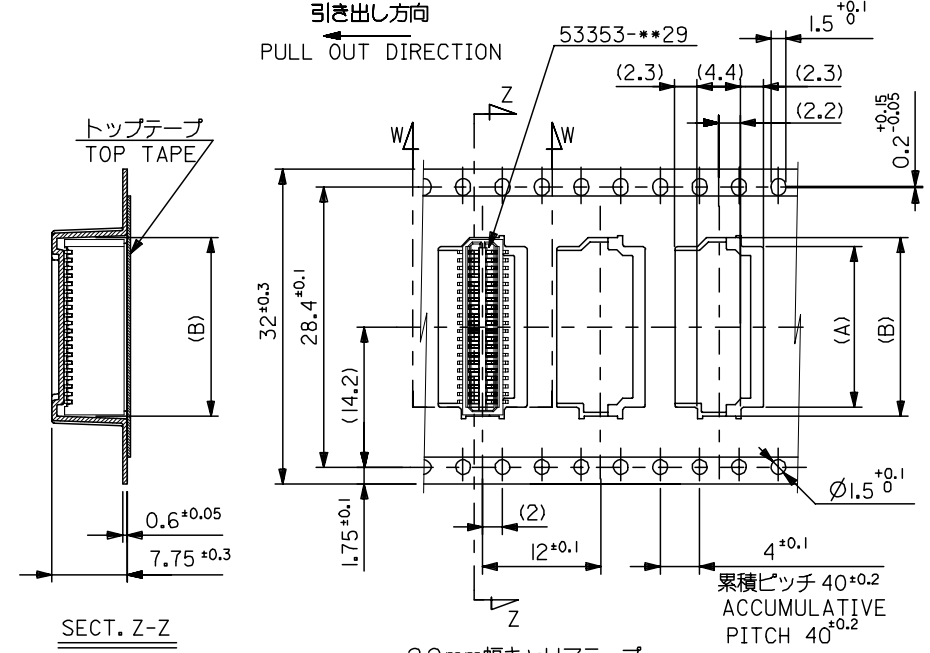
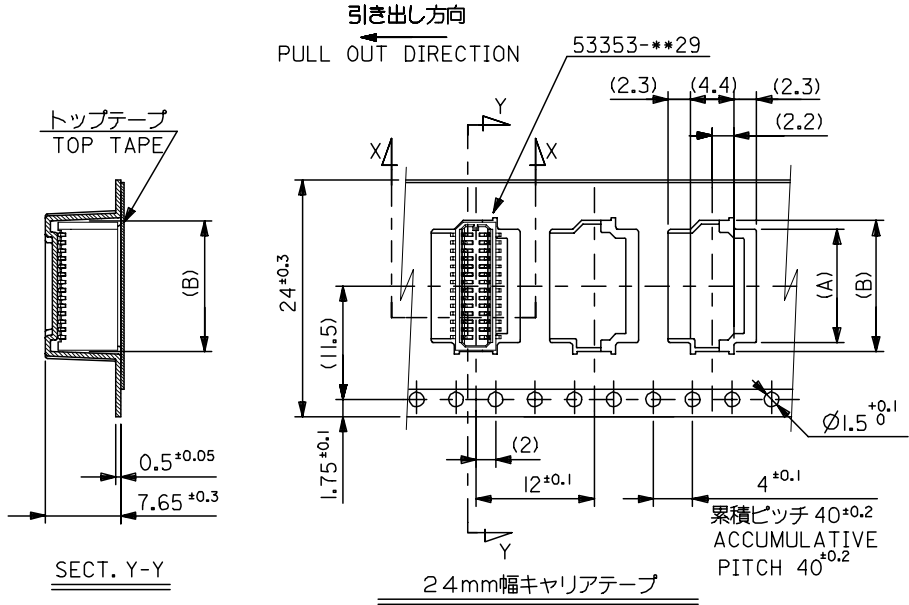


4. 材料 MATERIAL
キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE
トップテープ：PET, PE, PEF TOP TAPE:PET,PE,PEF
リール：ポリスチレン (PS) REEL:POLYSTYRENE(PS)
<リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>
5. 本製品は53353-**-91の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53353-**-91.

16	21.4	17.4	8.5	6.7	53353-1671	16
			7.7	5.9	53353-1471	14
			6.9	5.1	53353-1271	12
			6.1	4.3	53353-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

MODEL NO. 53353-**-71

REVISED EC NO: J2005-2159 DRAWN: KENSUJUKI 2005/01/26 CHKD: NUKITA 2005/01/26 APPR: NUKITA 2005/02/02 REV: A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2004/03/04	APPROVED BY MSASAO 2004/03/04		
	30 OVER	±0.3	APPROVED BY MSASAO 2004/03/04		MATERIAL NO. SEE CHART		
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53353-004	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



キャリアテープ幅 CARRIER TAPE WIDTH		D		C		(B)	(A)	MATERIAL NO.	極数 CIRCUIT
32	37.4	33.4	18.1	16.3	53353-4071	40			
			16.5	14.7	53353-3671	36			
24	29.4	25.4	14.1	12.3	53353-3071	30			
			13.3	11.5	53353-2871	28			
			10.9	9.1	53353-2271	22			
			10.1	8.3	53353-2071	20			
			9.3	7.5	53353-1871	18			

REVISED EC NO: J2005-2159 DRAWN: KENSUJUKI CHK'D: NUKITA APPR: NUKITA 2005/01/26 2005/01/26 2005/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE-	MOLEX INCORPORATED
	SEE CHART		DOCUMENT NO. SD-53353-004		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	MODEL NO. 53353-***71		SIZE A3						